

# EKOPRODUR DCP 2008

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| <b>CHEMICAL NAME</b>          | Polyurethane system  |
| <b>TECHNICAL REQUIREMENTS</b> | <p>Weight ratio of components POLY : ISO ..... 100 : 130</p> <p>Optimal components temperature: ..... 18 – 22°C</p> <p>Ambient temperature: ..... 15 – 25°C</p> <p>Optimal mould temperature: ..... 30 – 40°C</p> <p>EKOPRODUR DCP 2008 polyurethane system can be processed using low-pressure and high-pressure foaming machines. Foam achieves its final mechanical properties after 24h conditioning. During processing the system please keep in mind all tips and information included in the MSDS sheets for both components.</p>   |
| <b>GENERAL DATA</b>           | <p>Fire classification ..... F<br/>PN-EN 13501-1+A1:2010</p> <p>Coefficient of thermal conductivity: ..... <math>\lambda_{mean, i}</math> 0,022 W/(m·K)<br/>PN-EN 12667:2002</p> <p>Adhesion of the foam perpendicular to the grou ..... <math>\geq 280</math> kPa<br/>PN-EN 1607:2013-07</p> <p>Compressive stress at 10%<br/>relative strain, parallel: ..... <math>\sigma_{10} \geq 330</math> kPa<br/>PN-EN 826:2013-07</p> <p>Compressive stress at 10%<br/>relative strain, perpendicular: ..... <math>\sigma_{10} \geq 240</math> kPa<br/>PN-EN 826:2013-07</p> <p>Temperature stability:<br/>+ 70°C, 90% RH, after 24h ..... T +0,3 %<br/>L +0,3 %<br/>W +1,6 %</p> <p>-30°C, po 24h ..... T 0,0 %<br/>L 0,0 %<br/>W -0,2 %<br/>PN-EN 1605:2013-07</p> |
| <b>APPLICATION</b>            | EKOPRODUR DCP 2008 is used for insulation of refrigeration equipment and the production of insulation boards and panels in molds.  |